

CLAIMS

1. A protective film forming sheet formed by stacking a thermosetting resin layer on a first pressure-sensitive adhesive layer of a first supporting sheet,

5 wherein the first supporting sheet is formed by laminating at least a first base material and the first pressure-sensitive adhesive layer,

wherein the thermosetting resin layer is adhered to a surface having bumps of a semiconductor wafer and is cured by heat, whereby the first protective film is formed on the semiconductor wafer surface, and

10 a difference between a surface free energy of a first supporting sheet-side surface of the thermosetting resin layer before thermal curing and a surface free energy of a thermosetting resin layer-side surface of the first pressure-sensitive adhesive layer is 10 mJ/m² or more.

15 2. The protective film forming sheet according to Claim 1,

wherein a difference between a contact angle of the first supporting sheet-side surface of the thermosetting resin layer before thermal curing with respect to water and a contact angle of the thermosetting resin layer-side surface of the first pressure-sensitive adhesive layer with respect to water is 30° or more.

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